

# LB11967V

## Specifications

### Maximum Ratings at Ta = 25°C (Note1)

| Parameter                                   | Symbol                  | Conditions                           | Ratings     | Unit |
|---|-------------------------|--------------------------------------|-------------|------|
| V <sub>CC</sub> maximum supply voltage      | V <sub>CC</sub> max     |                                      | 18          | V    |
| OUT pin maximum output current              | I <sub>OUT</sub> max    |                                      | 50          | mA   |
| OUT pin output withstand voltage            | V <sub>OUT</sub> max    |                                      | 18          | V    |
| HB maximum output current                   | I <sub>HB</sub> max     |                                      | 10          | mA   |
| V <sub>TH</sub> input pin withstand voltage | V <sub>VTH</sub> max    |                                      | 8           | V    |
| RD/FG output pin output withstand voltage   | V <sub>RD/VFG</sub> max |                                      | 18          | V    |
| RD/FG output current                        | I <sub>RD/IFG</sub> max |                                      | 10          | mA   |
| Allowable power dissipation                 | Pd max                  | Mounted on a specified board (Note2) | 800         | mW   |
| Operating temperature range                 | Topr                    |                                      | -30 to +95  | °C   |
| Storage temperature range                   | Tstg                    |                                      | -55 to +150 | °C   |

1. Stresses exceeding those listed in the Maximum Rating table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.
2. Specified board: 114.3mm × 76.1mm × 1.6mm, glass epoxy board.

### Recommended Operating Conditions at Ta = 25°C (Note3)

| Parameter                                   | Symbol           | Conditions      | Ratings  | Unit |
|---|------------------|-----------------|----------|------|
| V <sub>CC</sub> supply voltage              | V <sub>CC</sub>  |                 | 6 to 16  | V    |
| V <sub>TH</sub> input level voltage range   | V <sub>TH</sub>  | Full speed mode | 0 to 7   | V    |
| Hall input common phase input voltage range | V <sub>ICM</sub> |                 | 0.2 to 3 | V    |

3. Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

### Electrical Characteristics at Ta = 25°C, V<sub>CC</sub> = 12V, unless otherwise specified. (Note4)

| Parameter                          | Symbol                | Conditions   | Ratings |      |      | Unit |
|------------------------------------|-----------------------|--|---------|------|------|------|
|                                    |                       |  | min     | typ  | max  |      |
| Circuit current                    | I <sub>CC1</sub>      | During drive   | 6       | 10   | 14   | mA   |
|                                    | I <sub>CC2</sub>      | During lock protection                               | 6       | 10   | 14   | mA   |
| 6VREG voltage                      | 6VREG                 | I <sub>6VREG</sub> = 5mA                             | 5.80    | 6.0  | 6.15 | V    |
| HB voltage                         | V <sub>HB</sub>       | I <sub>HB</sub> = 5mA                                | 1.05    | 1.22 | 1.35 | V    |
| VOVER voltage                      | V <sub>VOVER</sub>    | I <sub>VOVER</sub> = 1mA                             | 12.0    | 12.8 | 13.6 | V    |
| CPWM-H level voltage               | V <sub>CRH</sub>      |  | 4.35    | 4.55 | 4.75 | V    |
| CPWM-L level voltage               | V <sub>CRL</sub>      |  | 1.45    | 1.65 | 1.85 | V    |
| CPWM oscillation frequency         | FPWM                  | C = 100pF  | 18      | 25   | 32   | kHz  |
| CT pin H level voltage             | V <sub>CTH</sub>      |  | 3.4     | 3.6  | 3.8  | V    |
| CT pin L level voltage             | V <sub>CTL</sub>      |  | 1.4     | 1.6  | 1.8  | V    |
| ICT pin charge current             | I <sub>CT1</sub>      | V <sub>CT</sub> = 1.2V                               | 1.6     | 2.0  | 2.5  | μA   |
| ICT pin discharge current          | I <sub>CT2</sub>      | V <sub>CT</sub> = 4.0V                               | 0.16    | 0.20 | 0.28 | μA   |
| ICT charge/discharge current ratio | RCT                   | I <sub>CT1</sub> /I <sub>CT2</sub>                   | 8       | 10   | 12   | deg  |
| OUT-N output voltage               | V <sub>ON</sub>       | I <sub>O</sub> = 20mA                                | 4       | 10   |      | V    |
| OUT-P sink current                 | I <sub>OP</sub>       |  | 15      | 20   |      | mA   |
| Hall input sensitivity             | V <sub>HN</sub>       | Zero peak value<br>(including offset and hysteresis) |         | 10   | 20   | mV   |
| RD/FG output pin L voltage         | V <sub>RD/VFG</sub>   | I <sub>RD/IFG</sub> = 5mA                            |         | 0.15 | 0.3  | V    |
| RD/FG output pin leak current      | I <sub>RDL/IFGL</sub> | V <sub>RD/VFG</sub> = 16V                            |         |      | 30   | μA   |

4. Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

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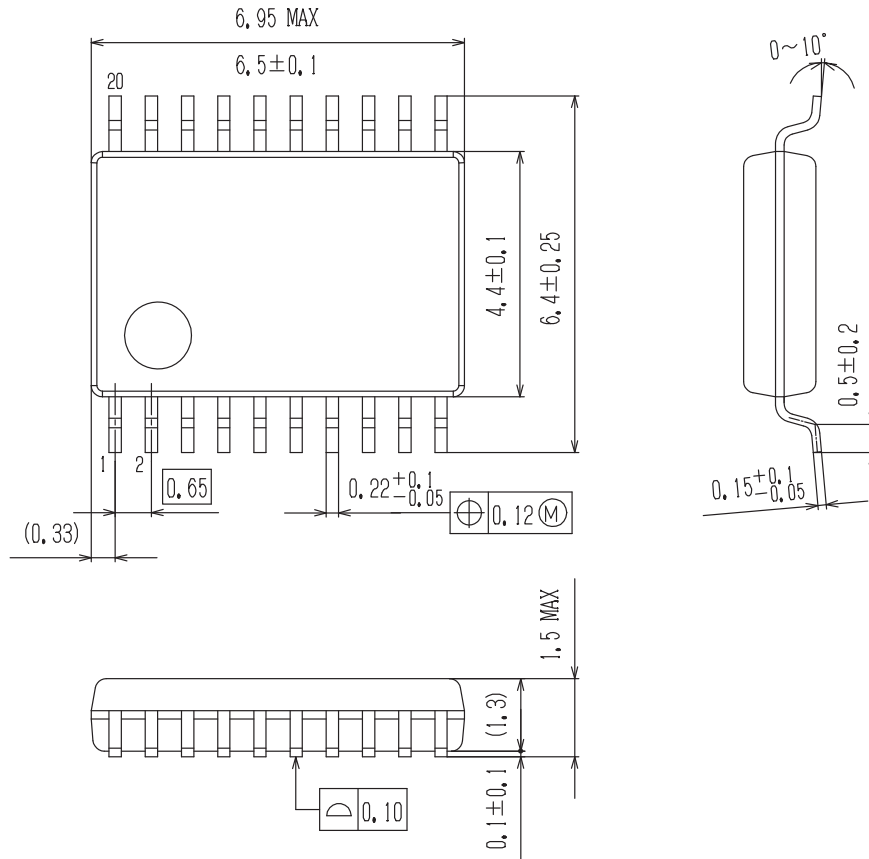
## Package Dimensions

unit : mm

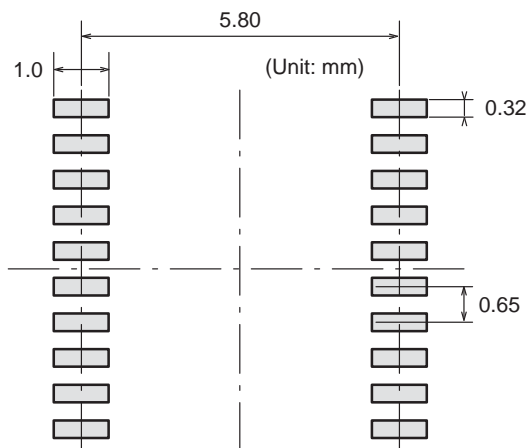
### SSOP20 (225mil)

CASE 565AN

ISSUE A



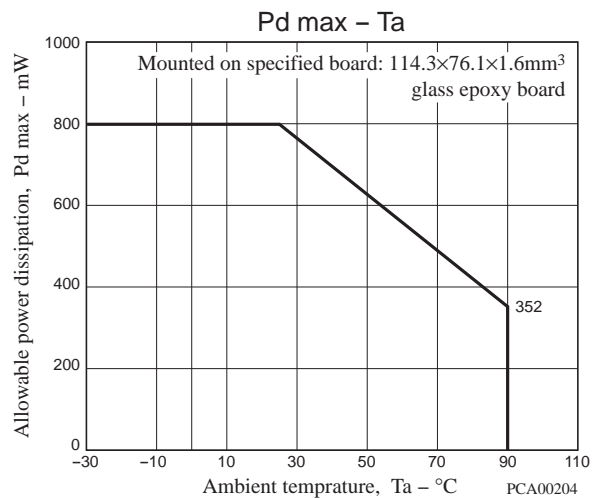
### SOLDERING FOOTPRINT\*



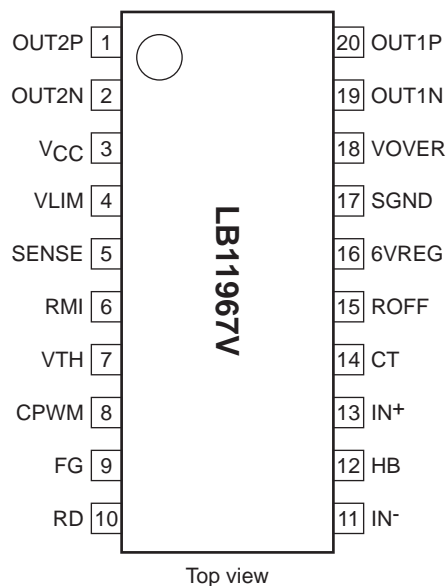
NOTE: The measurements are not to guarantee but for reference only.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERM/D.

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Pin Assignment



Truth Table

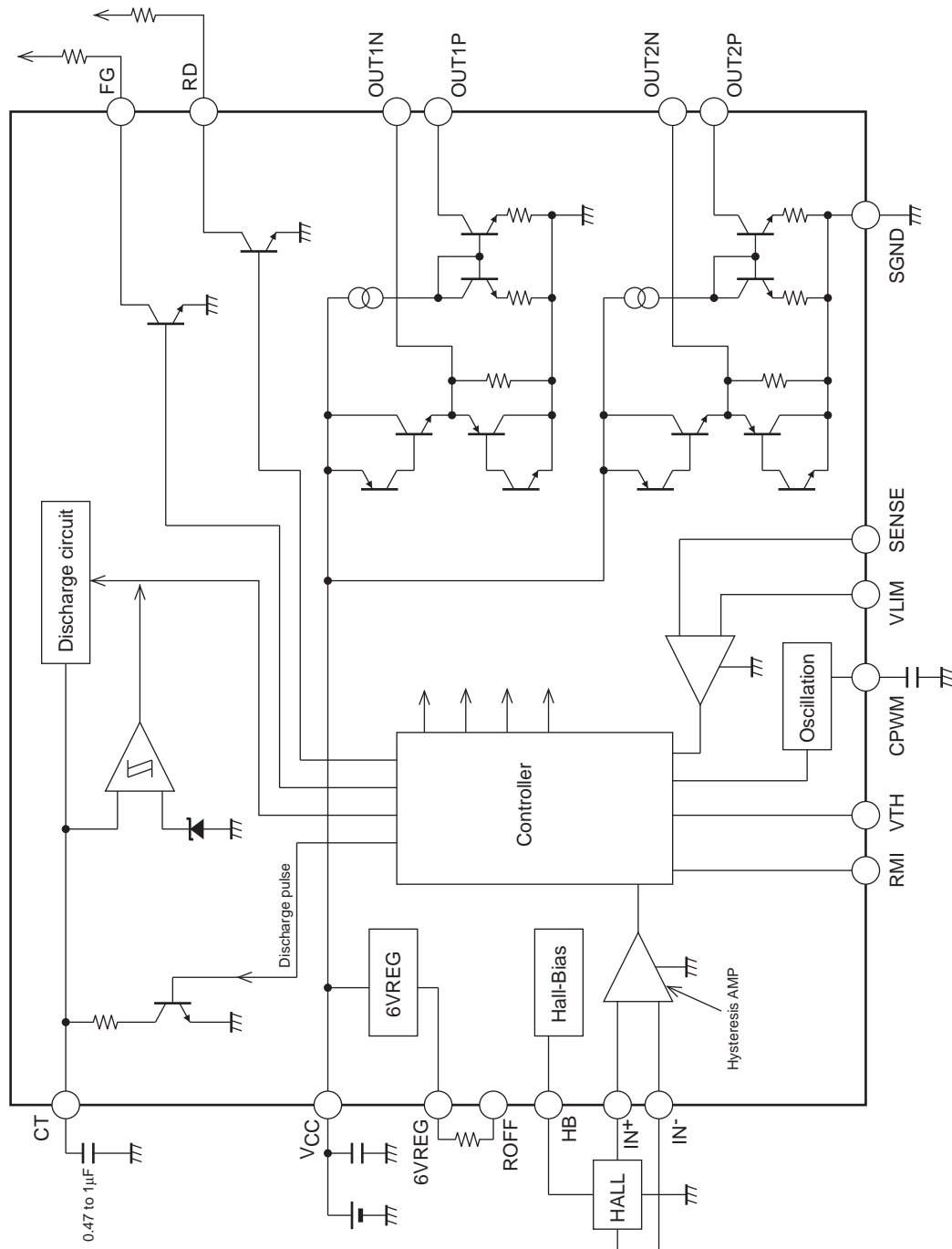
During full-speed rotation

| IN <sup>-</sup> | IN <sup>+</sup> | CT | OUT1P | OUT1N | OUT2P | OUT2N | FG  | RD  | Mode            |
|-----------------|-----------------|----|-------|-------|-------|-------|-----|-----|-----------------|
| H               | L               | L  | L     | L     | OFF   | H     | L   | L   | OUT1 → 2 drive  |
| L               | H               |    | OFF   | H     | L     | L     | OFF |     | OUT2 → 1 drive  |
| H               | L               | H  | OFF   | L     | OFF   | H     | L   | OFF | Lock protection |
| L               | H               |    | OFF   | H     | OFF   | L     | OFF |     |                 |

| VTH | CPWM | IN <sup>-</sup> | IN <sup>+</sup> | OUT1P | OUT1N | OUT2P | OUT2N | Mode  |
|-----|------|-----------------|-----------------|-------|-------|-------|-------|---|
| L   | H    | H               | L               | L     | L     | OFF   | H     | OUT1 → 2 drive                              |
|     |      | L               | H               | OFF   | H     | L     | L     | OUT2 → 1 drive                              |
| H   | L    | H               | L               | OFF   | L     | OFF   | H     | During rotation<br>Regeneration in lower Tr |
|     |      | L               | H               | OFF   | H     | OFF   | L     |   |

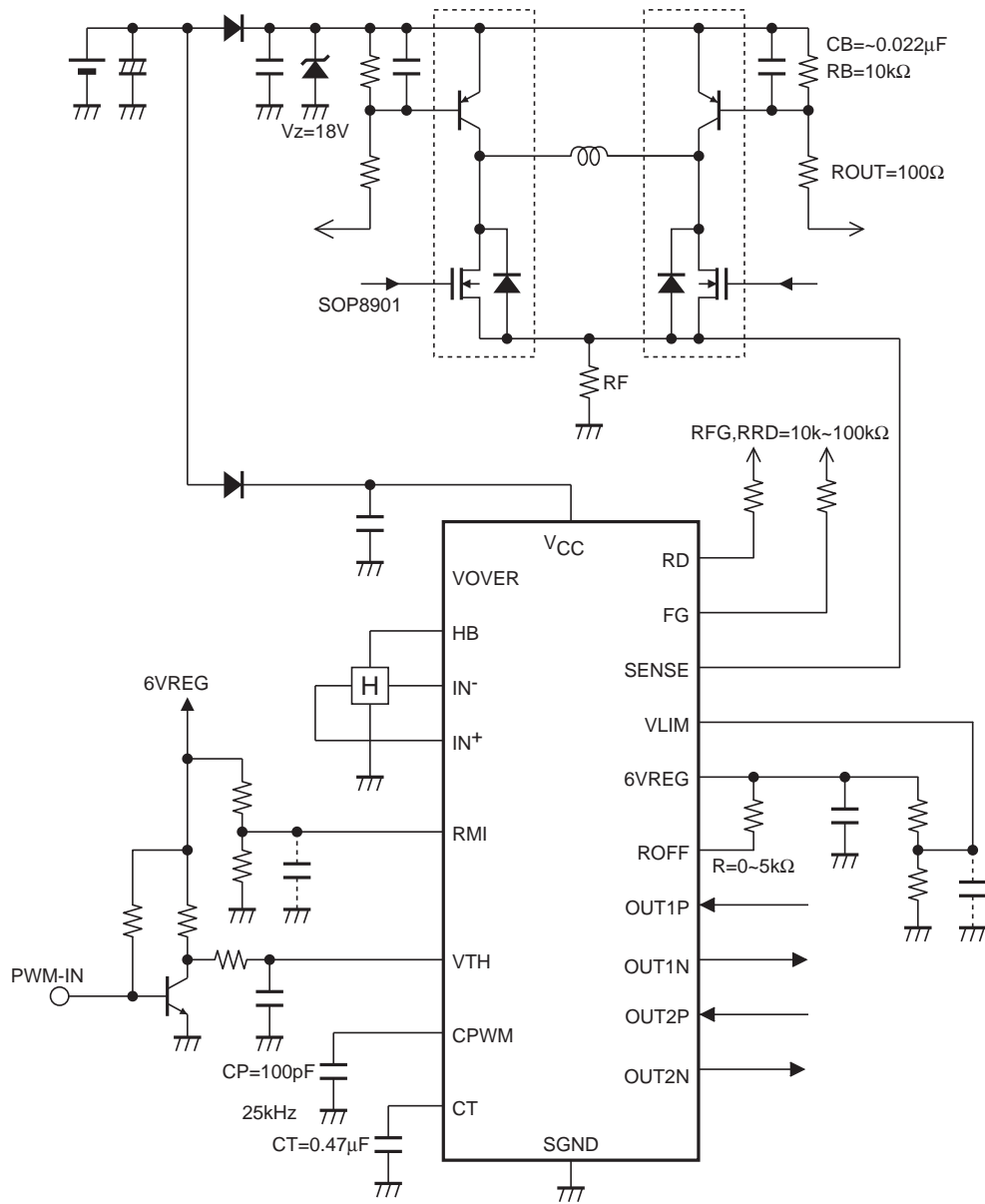
# LB11967V

## Block Diagram



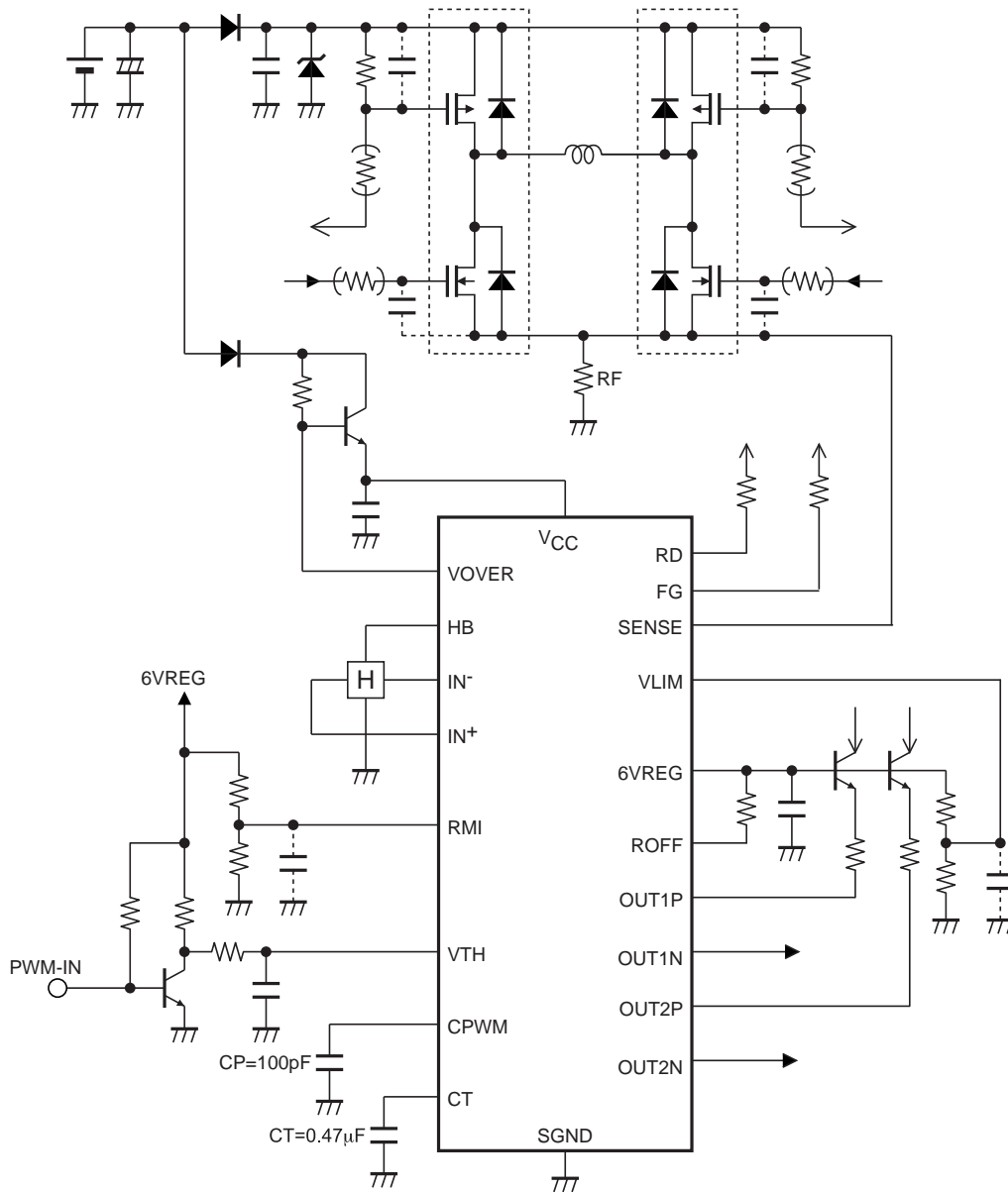
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## Sample Application Circuit 1 (12V)



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## Sample Application Circuit 2 (24V, 48V)



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\*1. <Power supply-GND wiring>

SGND is connected to the control circuit power supply system.

\*2. <Power stabilization capacitor for regeneration>

For the CM capacitor that is a power stabilization capacitor for PWM drive and for absorption of kick-back, the capacitance uses 0.1 $\mu$ F or more. In this IC, the lower Transistor performs current regeneration by means of switching of upper Transistor. Connect CM between V<sub>CC</sub> and GND with the thick pattern and along the shortest route.

\*3. <Zener diode to stabilize power supply for regeneration>

Be sure to use the zener diode if kick-back causes excessive increase of the supply voltage because such increase damages IC.

\*4. <Hall input>

Wiring need to be short to prevent carrying of the noise. If the noise is carried, insert a capacitor between IN+ and IN-. The Hall input circuit is a comparator having a hysteresis of 20mV. It is recommended that the Hall input level is more than three times (60mVp-p) this hysteresis.

\*5. <Capacitor to set the PWM oscillation frequency>

With CP = 100pF, oscillation occurs at f = 25kHz and provides the basic frequency of PWM.

\*6. <RD output>

This is the open collector output, which outputs “L” during rotation and “H” at stop. This output is left open when not used.

\*7. <FG output>

This is the open collector output, which can detect the rotation speed using the FG output according to the phase shift. This output is left open when not used.

\*8. <HB pin>

This is a Hall element bias pin, that is, the constant-voltage output pin.

\*9. <RMI pin>

This is the minimum speed setting pin, which is pulled up with 6VREG when not used.

When IC power may possibly be turned OFF first when the pin is used, be sure to insert a current limiting resistor to prevent inflow of the large current. (The same applies to the VTH pin.)

\*10. <ROFF pin>

This pin sets the soft switching time to cut the reactive current before phase change and is connected to 6VREG when not used.

\*11. <VLIM pin>

This pin activates the current limiter when the SENSE pin voltage is higher than the VLIM pin voltage and is connected to 6VREG when not used.

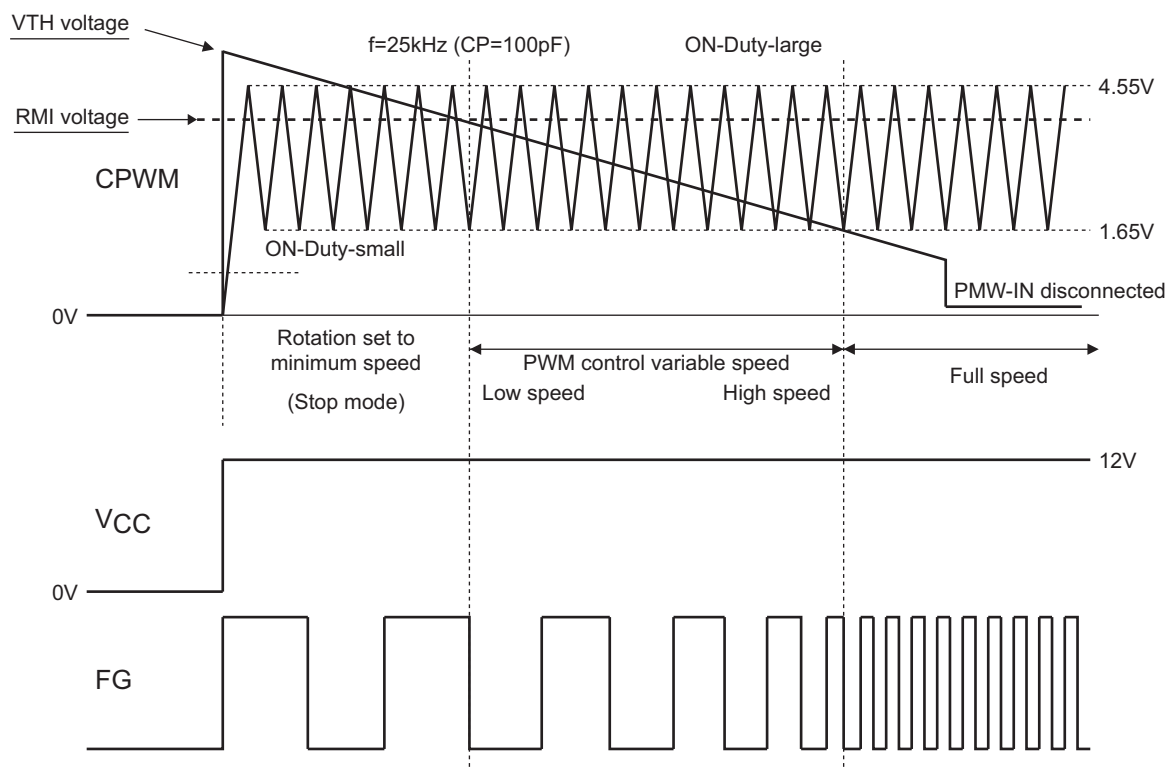
\*12. <SENSE pin>

This is connected to GND when not used.

\*13. <VOVER pin>

This is a pin for constant-voltage bias and should be used for application of 24V and 48V. (Refer to the sample application circuit.) Be sure to use the current limiting resistor. This is left open when not used.

## Control Timing Chart



## (1) Minimum speed setting (stop) mode

PWM-IN input is filtered to generate the VTH voltage. At low speed, the fan rotates with the minimum speed set with RMI pin during low speed. If the minimum speed is not set ( $RMI = 6V_{REG}$ ), the fan stops.

(2) Low $\leftrightarrow$ High speed mode

PWM control is made through comparison of oscillation and VTH voltages with CPWM changing between  $1.6V \leftrightarrow 4.6V$ . When the VTH voltage is lower, the IC switches to drive mode. When the VTH voltage is higher, the p-channel FET is turned off and coil current is regenerated through the low-side FET. Therefore, as the VTH voltage lowers, the output ON-DUTY increases, increasing the coil current and raising the motor speed. The rotation speed is fed back by the FG output.

## (3) Full speed mode

The full-speed mode becomes effective with the VTH voltage of 1.65V or less. (VTH must be equal to GND when the speed control is not to be made.)

## (4) PWM-IN input disconnection mode

When the PWM-IN input pin is disconnected, VTH becomes 1.65V or less and the output enables full drive at 100%. The fan runs at full speed. (Refer to the sample application circuit.)



## LB11967V

### ORDERING INFORMATION

| Device         | Package                                    | Wire Bond | Shipping(Qty/Packing) |
|----------------|--|-----------|-----------------------|
| LB11967V-MPB-H | SSOP20(225mil)<br>(Pb-Free / Halogen Free) | Au-wire   | 70 / Fan-fold         |
| LB11967V-TLM-H | SSOP20(225mil)<br>(Pb-Free / Halogen Free) | Au-wire   | 2000 / Tape & Reel    |
| LB11967V-W-AH  | SSOP20(225mil)<br>(Pb-Free / Halogen Free) | Cu-wire   | 2000 / Tape & Reel    |

† For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D. [http://www.onsemi.com/pub\\_link/Collateral/BRD8011-D.PDF](http://www.onsemi.com/pub_link/Collateral/BRD8011-D.PDF)

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